Amendments to the Claims:

This listing of Claims will replace all prior versions, and listings, of claims in the application.

Claim 1 (Currently Amended) A multichip module structure, at least comprising:

a first multichip module substrate, comprising:

a semiconductor substrate having a first surface and a second surface;

an insulating layer on said first surface;

a multilayer interconnection structure on said insulating layer and having a third surface having a plurality of first bonding pads and a fourth surface having a plurality of second bonding pads and on said insulating layer without contacting said semiconductor substrate;

a plurality of conductive plugs penetrating through said semiconductor substrate and said insulating layer and electrically connecting to said second bonding pads respectively;

a plurality of third bonding pads on said second surface and connecting to said conductive plugs respectively; and

a plurality of chips on said second surface and electrically connecting to said third bonding pads.

Claim 2 (Original) The multichip module structure according to

claim 1, wherein said multilayer interconnection structure includes at least one integrated circuit device.

Claim 3 (Previously Presented) The multichip module structure according to claim 1, wherein said semiconductor substrate has a thickness between 10 to 500 micron.

Claim 4 (Original) The multichip module structure according to claim 1, wherein said chip is an active chip.

Claim 5 (Original) The multichip module structure according to claim 4, wherein said active chip is mounted on said second surface by flip-chip type.

Claim 6 (Original) The multichip module structure according to claim 1, wherein said chip is a passive chip.

Claim 7 (Original) The multichip module structure according to claim 1, wherein said chips individually and electrically connect to said third bonding pads.

Claim 8 (Previously Presented) The multichip module structure according to claim 1, wherein said plurality of chips comprise a first

active chip mounted on said said second surface by flip-chip type, and at least one chip electrically connecting and stacking on a backside of said first active chip.

Claim 9 (Original) The multichip module structure according to claim 8, wherein said at least one chip comprises a second active chip mounted on said backside of said first active chip by flip-chip type.

Claim 10 (Original) The multichip module structure according to claim 8, wherein said at least one chip comprises a passive chip.

Claim 11 (Original) The multichip module structure according to claim 1, further comprising a second multichip module substrate on said third surface, wherein said second multichip module substrate has a same structure as said first multichip module substrate.

Claim 12 (Previously Presented) The multichip module structure according to claim 1, wherein said multichip module structure is further electrically connected with a package substrate on said third surface.

Claims 13-24 (Canceled)